Product Change Notification

Change Notification #:	**115267 - 02**
Change Title:	**Intel® NUC Board DE3815TYBE and Intel® NUC Kit DE3815TYKHE, PCN 115267-02, Product Design, Label, Product Material, New fab spin change, E3815 CPU B3 to D0 stepping conversion, Change eMMC from 4GB to 8GB storage, BIOS update, Reason for Revision: Revise Dates for BLKDE3815TYBE availability and add new BIOS version ID**
Date of Publication:	**March 09, 2017**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

	BLKDE3815TYBE	**BLKDE3815TYKH0E**
Date of Samples Availability:	Feb 16, 2017	Dec 14, 2017
Date of Qualification Data Availability:	Feb 16, 2017	Dec 14, 2017
Date Customer Must be Ready to Receive Post-Conversion Material:	**Mar 16, 2017**	Dec 21, 2017
Date of First Availability of Post-Conversion Material:	**Mar 16, 2017**	Dec 21, 2017

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Reason for Revision: Revise Dates for BLKDE3815TYBE availability and add new BIOS version ID

The Intel® NUC SKUs listed in the products affected table below will have the following change.

1. Printed Circuit Board Change to enhance product features by replacing of Super IO controller with Embedded Controller (EC)

2. Component, Add Piezo Speaker and full Serial Port support.

3. Increase eMMC capacity from 4GB to 8GB

4. Intel® ATOM Processor stepping change from B3 to D0 to support product continuity.

5. The new Bios TYBYT20H.86A.0009 is implemented to support product feature enhancement needs and is not compatible with older versions of the product.

Customer Impact of Change and Recommended Action:

It is recommended that customers evaluate this new product enhancements to ensure a smooth transition. These changes have been thoroughly evaluated to ensure that there are no quality or reliability implication to our customers.

Milestone dates are estimates and subject to change based on business and operational conditions.

Customer can expect to receive mixed inventory until current inventory levels are depleted.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change SA	Pre Change AA	Post Change SA	Post Change AA
BLKDE3815TYKH0E	933135	H27002-404	H26998-405	H27002-500	H26998-500
BLKDE3815TYBE	933136		H26998-405		H26998-500

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
January 19, 2017	00	Originally Published PCN
February 14, 2017	01	Addition of separate Milestone dates for BLKDE3815TYKH0E.
March 9, 2017	02	Revise Dates for BLKDE3815TYBE availability and add new BIOS version ID

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
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